

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10710884
<b>Filing Date:</b>	10-Aug-2004
<b>Title of Invention:</b>	METHOD OF SOLDERING SEMICONDUCTOR PART AND MOUNTED STRUCTURE OF SEMICONDUCTOR PART
<b>First Named Inventor/Applicant Name:</b>	Akihiro Mano
<b>Filer:</b>	Larry Joe Hume/Amanda Childs
<b>Attorney Docket Number:</b>	22040-00034-US1

Filed as Small Entity

Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appl issue fee	2501	1	700	700
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1000